



# Material Composition Declaration

## EPC2152

Company Name	Efficient Power Conversion (EPC)	Issue Date:	12/12/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	14.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	11.4901	82.3555	85.7609	823555
	Silicon oxide	7631-86-9	0.1017	0.7289		7289
	Silicon nitride	12033-89-5	0.0157	0.1122		1122
	Gallium nitride	25617-97-4	0.0741	0.5311		5311
	Aluminum	7429-90-5	0.1107	0.7935		7935
	Aluminum nitride	24304-00-5	0.0143	0.1024		1024
	Titanium	7440-32-6	0.0030	0.0216		216
	Titanium nitride	25583-20-4	0.0537	0.3849		3849
	Copper	7440-50-8	0.0018	0.0132		132
	Tungsten	7440-33-7	0.0061	0.0438		438
	Polyimide		0.0940	0.6737		6737
Under Bump Metal	Titanium	7440-32-6	0.0016	0.0116	0.1267	116
	Copper	7440-50-8	0.0161	0.1151		1151
Solder Bump	Copper	7440-50-8	0.1606	1.1508	14.1125	11508
	Nickel	7440-02-0	0.0958	0.6865		6865
	Tin	7440-31-5	1.6818	12.0543		120543
	Silver	7440-22-4	0.0308	0.2210		2210
Sum in total:			13.9518	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.